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Williams et al.

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(54) **LEADFRAME MATRIX FOR A SURFACE MOUNT PACKAGE**

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(**) Term: **14 Years**

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(51) **LOC (7) Cl.** **13-03**
(52) **U.S. Cl.** **D13/182**; D13/184
(58) **Field of Search** D9/345; D13/182, D13/184; 174/52.4; 206/714, 715, 716, 713, 727, 728

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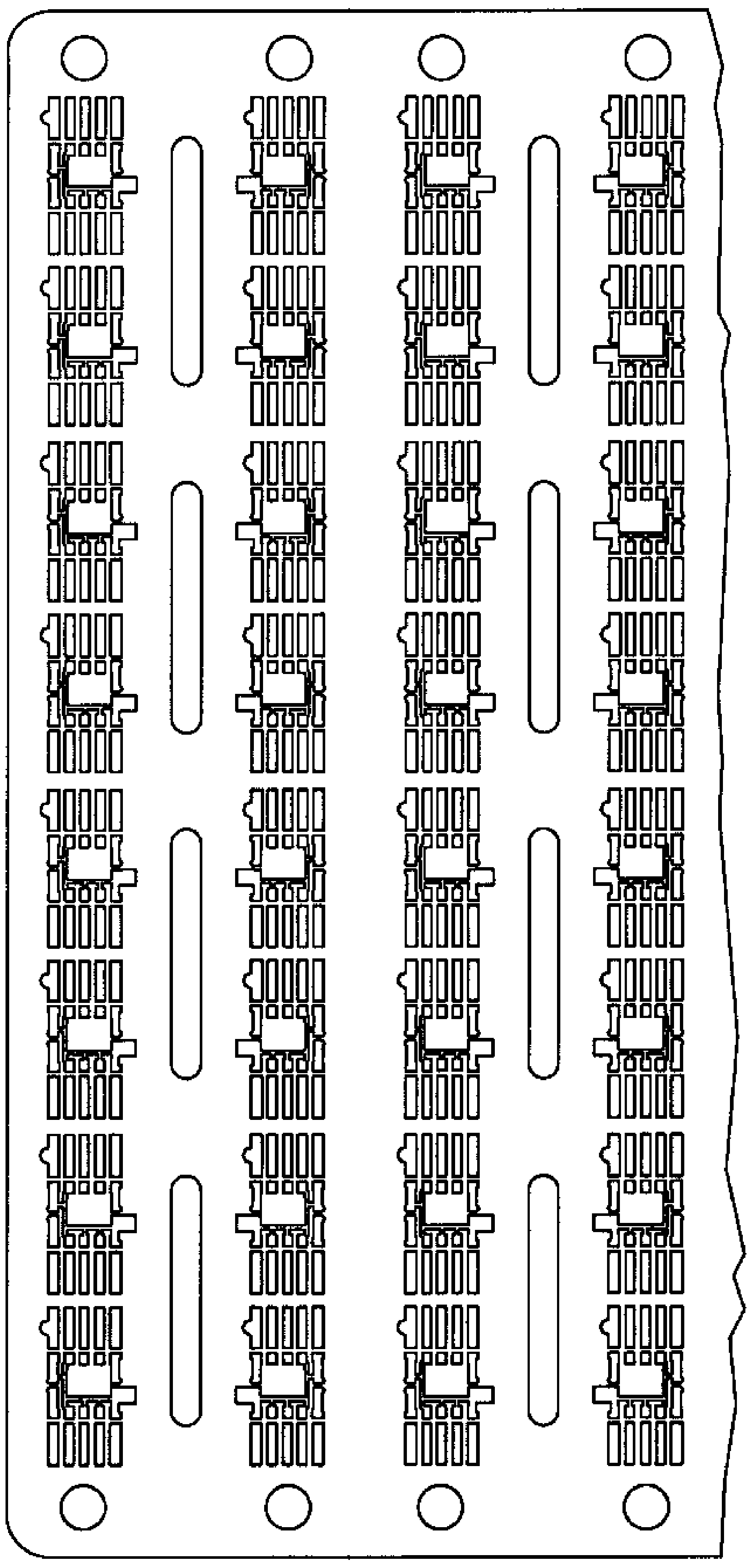
(57) **CLAIM**

The ornamental design for leadframe matrix for a surface mount package, as shown and described.

DESCRIPTION

FIG. **1** is a top plan view of a portion of a leadframe matrix for a surface mount package showing my new design;
FIG. **2** is a top plan view of a single surface mount package shown at a lager scale for clarity of illustration; and,
FIG. **3** is a perspective view of FIG. **1**.
The leadframe matrix for a surface mount package is shown broken away in FIGS. **1** and **3** of the drawing to indicate indeterminant length, it being understood that it has a uniform shape and appearance throughout its length.

1 Claim, 3 Drawing Sheets



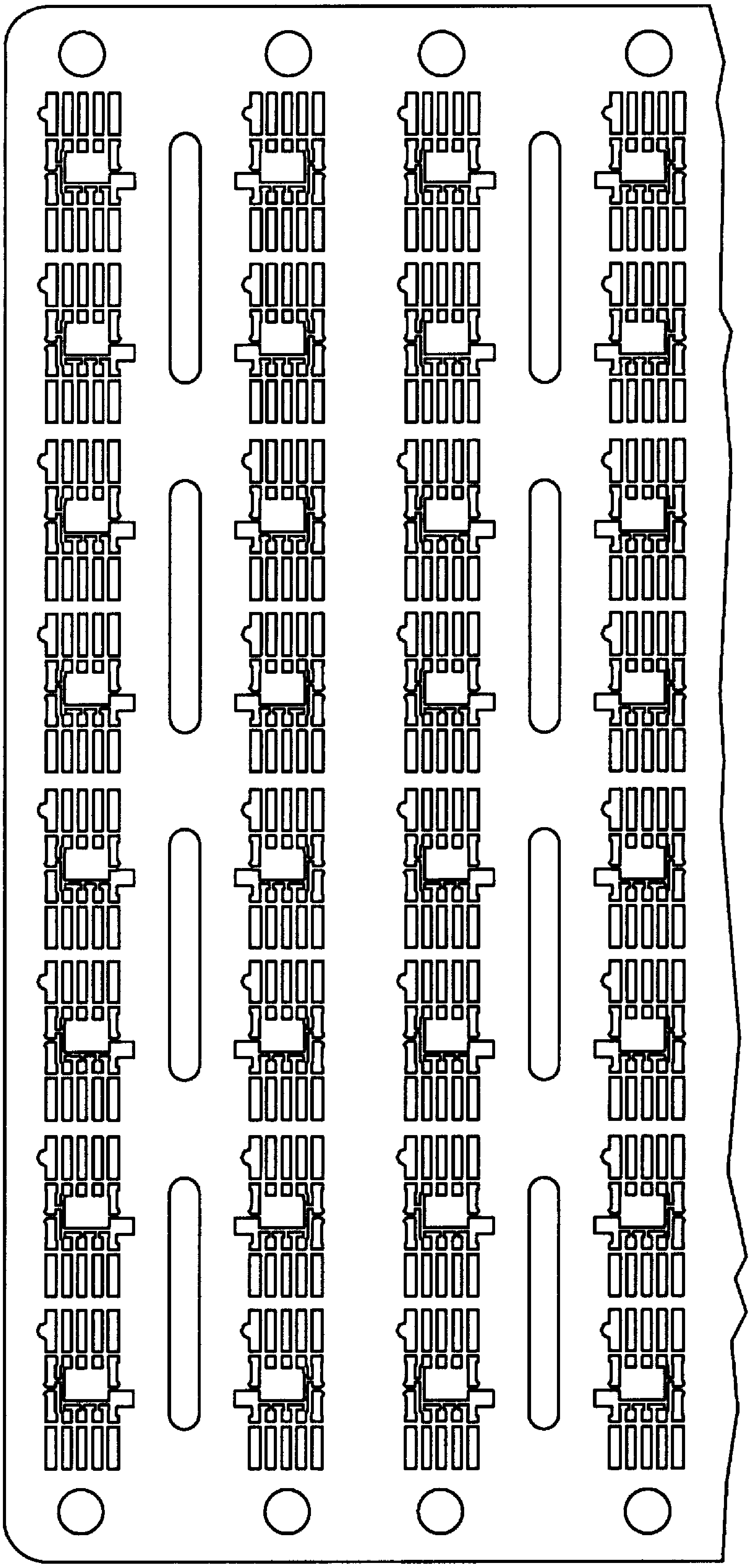


FIG. 1

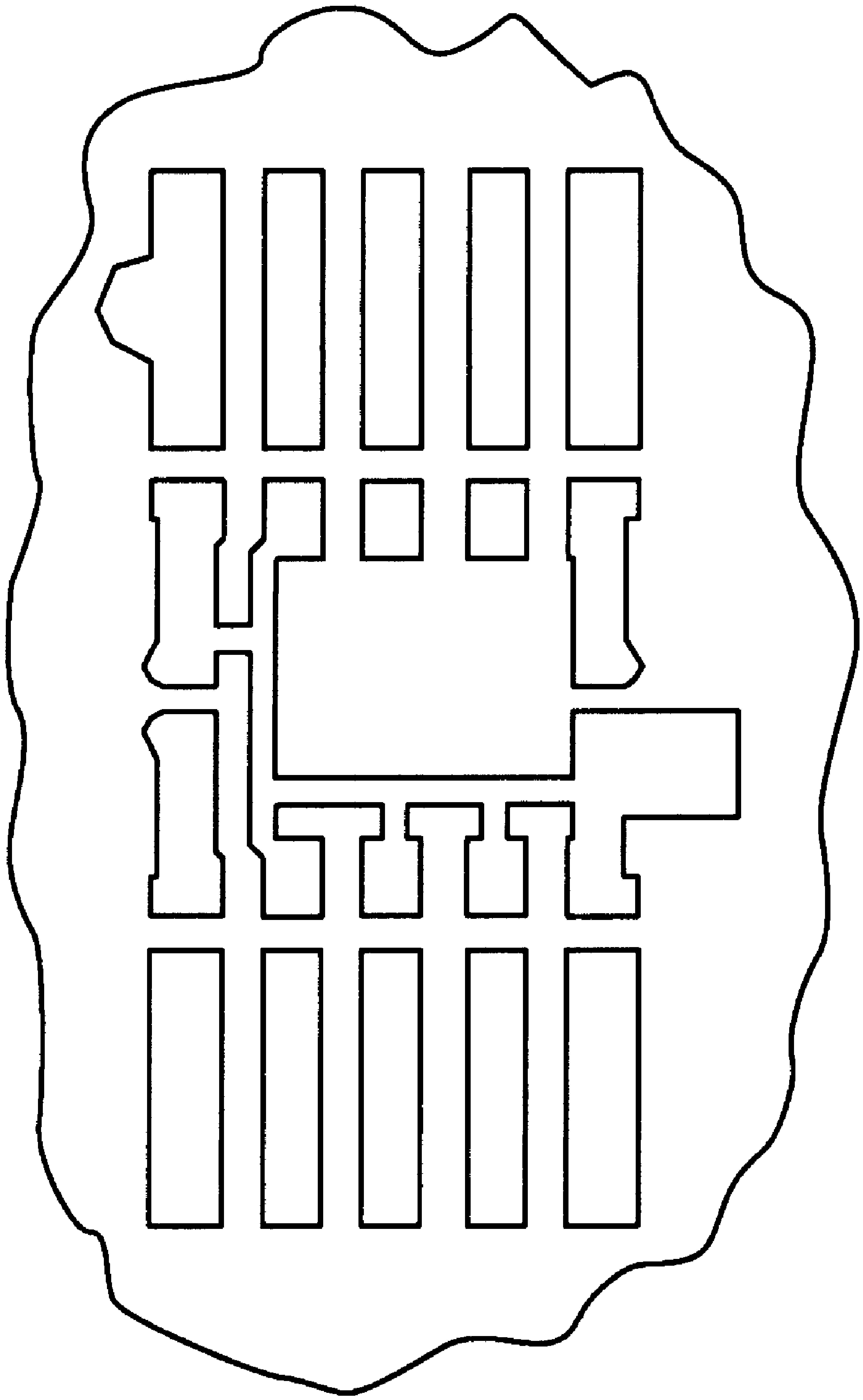


FIG. 2

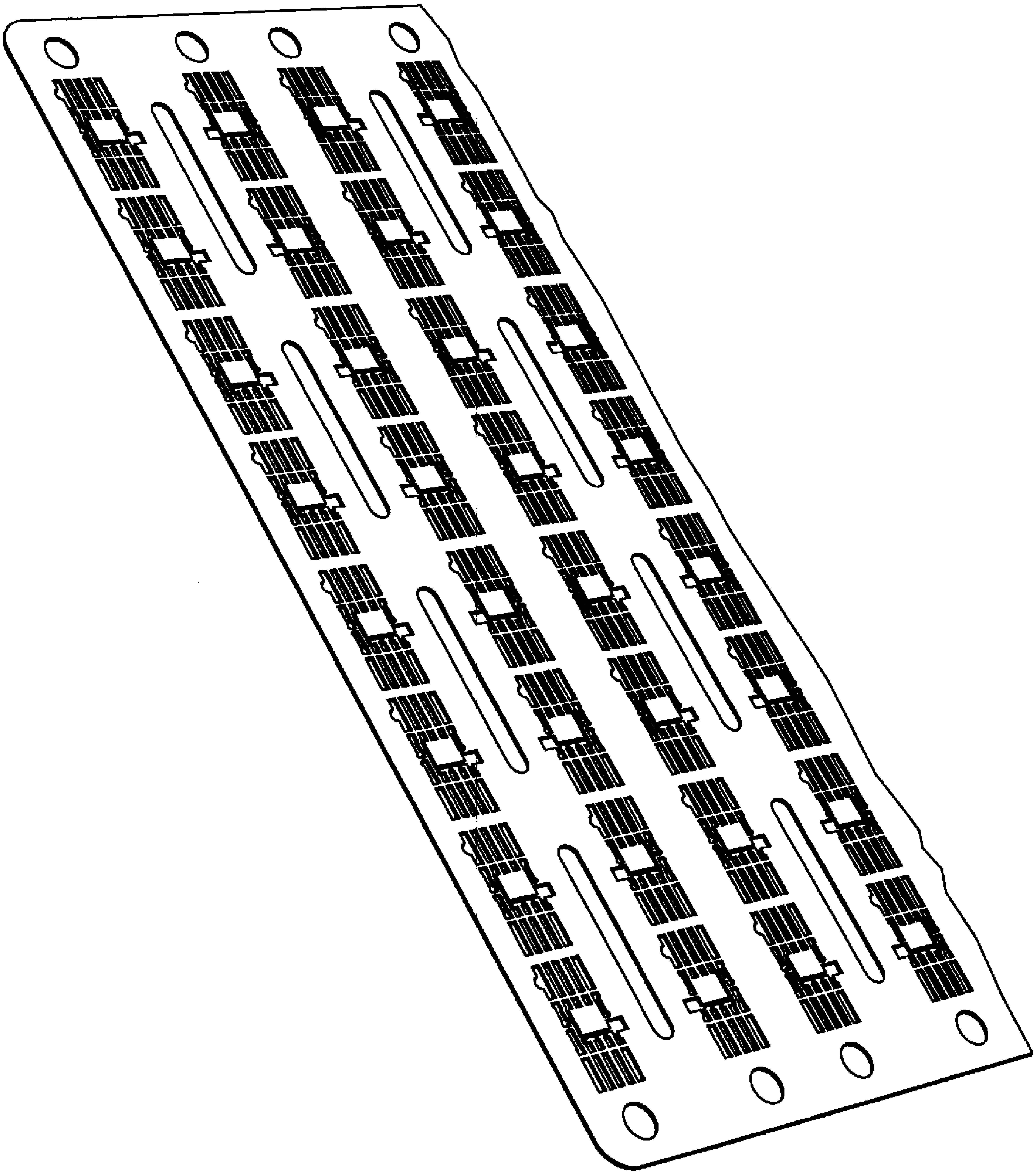


FIG. 3